



Material Content Data Sheet



Sales Product Name		BBY 66-05W H6327		Issued		19. December 2014		
MA#		MA000850034						
Package		PG-SOT323-3-1		Weight*		5.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.005	0.09		895	
	non noble metal	arsenic	7440-38-2	0.000	0.00		9	
	inorganic material	silicon	7440-21-3	0.091	1.53	1.62	15284	16188
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		440	
	non noble metal	chromium	7440-47-3	0.008	0.13		1319	
	non noble metal	copper	7440-50-8	2.617	43.79	43.97	437914	439761
wire	non noble metal	copper	7440-50-8	0.013	0.22	0.22	2207	2207
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5180	
	plastics	epoxy resin	-	0.665	11.14		111362	
	inorganic material	silicondioxide	60676-86-0	2.399	40.14	51.80	401421	517963
leadfinish	non noble metal	tin	7440-31-5	0.133	2.22	2.22	22206	22206
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1675	1675
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com